

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	589	385/91	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:45
L2	2155	385/92	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:45
L3	1166	385/93	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:45
L4	824	385/94	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:46
L5	566	385/38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:46
L6	2521	372/6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:46
L7	1426	372/36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:46
L8	3811	372/50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:46
L9	887	437/211	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:46
L10	11026	1 or 2 or 3 or 4 or 5 or 6 or 7 or 8 or 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:46

L11	5	10 and semiconductor and waveguide and (plastic near3 body)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:49
S1	8	(semiconductor near5 laser) and substrate and (optic\$3 near3 (fiber or waveguide)) and ((plastic or thermoplast or duroplast) near5 body) and (coolant or water) and lens and glass	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 09:20
S2	0	(semiconductor near5 laser) and (substrate near8 lead) and (optic\$3 near3 (fiber or waveguide)) and ((thermoplast or duroplast) near5 body) and ((heat or thermal) near8 (microchannel or microplate or micropore)) and (coolant or water) and (len near5 cylind\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 08:45
S3	0	(semiconductor near5 laser) and (substrate near6 metal) and (optic\$3 near3 (fiber or waveguide)) and ((thermoplast or duroplast) near5 body) and ((heat or thermal) near8 (microchannel or microplate or micropore)) and (coolant or water) and (len near5 cylind\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 08:57
S4	0	(semiconductor near5 laser) and (substrate) and (optic\$3 near3 (fiber or waveguide)) and ((thermoplast or duroplast) near6 (housing or casing or protect\$4 or body)) and ((heat or thermal) near8 (microchannel or microplate or micropore)) and (coolant or water) and (len near5 cylind\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 09:00
S5	0	(semiconductor near5 laser) and (substrate) and (optic\$3 near3 (fiber or waveguide)) and ((thermoplast or duroplast) near6 (housing or casing or protect\$4 or body)) and (coolant or water) and (len near5 cylind\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 09:00
S6	0	(semiconductor near5 laser) and (substrate) and (optic\$3 near3 (fiber or waveguide)) and (plastic near6 (housing or casing or protect\$4 or body)) and ((heat or thermal) near8 (microchannel or microplate or micropore)) and (coolant or water) and (len near5 cylind\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 09:01

S7	4	(semiconductor near5 laser) and (substrate) and (optic\$3 near3 (fiber or waveguide)) and (plastic near6 (housing or casing or protect\$4 or body)) and (coolant or water) and (len near5 cylind\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 09:04
S8	16	("5668903", "5548605", "5516727", "5327443", "5309460", "5307362", "5218611").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 09:26
S9	4	("5311535", "5526373").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 09:27
S10	95	(thermoplast or duroplast) and resin and glass and opaque	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 16:00
S11	7	((thermoplast or duroplast) and resin and glass and opaque) and (semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 15:59
S12	143	(thermoplast or duroplast) and (glass or fill\$3) and opaque	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 16:01
S13	1	((thermoplast or duroplast) and (glass or fill\$3) and opaque) and (semiconductor near6 (laser or diode))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/14 16:01
S14	344	(semiconductor near5 laser) and substrate and (optic\$3 near3 (fiber or waveguide)) and (coat\$4 near6 silic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 09:22
S15	39	(semiconductor near5 laser) and substrate and (optic\$3 near3 (fiber or waveguide)) and (coat\$4 near6 silic\$4) and (cross near4 area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 09:50
S16	0	(semiconductor near5 laser) and substrate and ((optic\$3 near3 (fiber or waveguide)) near8 (coat\$4 near6 silic\$4)) and (cross near4 area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:02

S17	0	(semiconductor near5 laser) and substrate and ((optic\$3 near3 (fiber or waveguide)) near10 (coat\$4 near6 silic\$4)) and (cross near4 area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:08
S18	0	(semiconductor near5 laser) and ((optic\$3 near3 (fiber or waveguide)) near10 (coat\$4 near4 (silic\$4)) and polish\$3 and ((cross\$4 or cross\$1section\$3) near6 area))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:13
S19	4362	(semiconductor near5 laser) and (len near4 cylind\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:13
S20	293	(semiconductor near5 laser) and (len near4 cylind\$6) and (optic\$3 near3 waveguide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:14
S21	8	(semiconductor near5 laser) and (len near4 cylind\$6) and ((optic\$3 near3 waveguide) near silic\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:21
S22	0	(semiconductor near5 laser) and (len near4 cylind\$6) and ((optic\$3 near3 waveguide) near6 silic\$6 near6 polish\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:37
S23	4	(semiconductor near5 laser) and ((optic\$3 near3 waveguide) near6 silic\$6 near6 polish\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:40
S24	4	(semiconductor near5 laser) and ((optic\$3 near3 waveguide) near6 (coat\$4 near4 silic\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:42
S25	0	(semiconductor near5 laser) and ((optic\$3 near3 waveguide) near8 (polish\$4 near18 (advantage or benefit)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 14:20
S26	5	((optic\$3 near3 waveguide) near8 (polish\$4 near18 (advantage or benefit)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 10:54

S27	2	"5268978".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 11:09
S28	3	(semiconductor near5 laser) and ((optic\$3 near3 waveguide) near8 ((silicon near3 dioxide) near6 coat\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 14:22
S29	0	(semiconductor near5 laser) and ((optic\$3 near3 waveguide) near8 ((silicon near3 dioxide) near6 coat\$4)) and slant and polish	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 14:38
S30	0	((optic\$3 near3 waveguide) near8 ((silicon near3 dioxide) near6 coat\$4)) and slant and polish	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 14:40
S31	0	((optic\$3 near3 waveguide) near8 ((silic\$3) near6 coat\$4)) and slant and polish	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 14:41
S32	0	((optic\$3 near3 waveguide) near8 ((silic\$3) near6 coat\$4)) and polish	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 15:21
S33	1	laser and ((optic\$3 near3 (fiber or waveguide)) near8 (coat\$4)) and slant and polish	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 15:23
S34	610	385/94	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:28
S35	537	385/38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:28
S36	849	437/211	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:28

S37	2139	372/6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:28
S38	1198	372/36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:28
S39	3079	372/50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:29
S40	915	385/93	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:29
S41	1453	385/92	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:29
S42	463	385/91	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/01/15 16:29